



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2018-11-09
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Floriana SAN BIAGIO	Representative Title	AMS MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	KD6P*0358AE6	A	BO2A	2018-11-09
	Amount	UoM	Unit type	ST ECOPACK Grade
	34.89	mg	Each	ECOPACK® 3
Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	4.4x 3x 0.9	8	gull wing	
Comment	6P TSSOP 8 BODY 4.4 PITCH 0.65; MDF valid for LM358AWPT			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : ELV directive : 2000/53/EC amended 2017/2096 _November 2017	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
Exemption Id.	Description

QueryList : REACH-27th June 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
;				0
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	KD6P*0358AE6				5000000.0	899998.0
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	1.027	mg	supplier	die	Silicon (Si)	7440-21-3		1.010	mg	983447	28948
				supplier	metallization	Aluminium (Al)	7429-90-5		0.008	mg	7790	229
				supplier	Passivation	Silicon Nitride	12033-89-5		0.004	mg	3895	115
				supplier	Passivation	Silicon Oxide	7631-86-9		0.005	mg	4869	143
Leadframe	M-004 Copper and its alloys	13.737	mg	supplier	alloy	Copper (Cu)	7440-50-8		13.039	mg	949188	373717
				supplier	alloy	Nickel (Ni)	7440-02-0		0.407	mg	29628	11665
				supplier	alloy	Magnesium (Mg)	7439-95-4		0.020	mg	1456	573
				supplier	alloy	Silicon (Si)	7440-21-3		0.088	mg	6406	2522
				supplier	metallization	Nickel (Ni)	7440-02-0		0.166	mg	12084	4758
				supplier	metallization	Palladium (Pd)	7440-05-3		0.005	mg	364	143
				supplier	metallization	Gold (Au)	7440-57-5		0.009	mg	655	258
				supplier	metallization	Silver (Ag)	7440-22-4		0.003	mg	218	86
Die attach	M-015 Other organic materials	0.403	mg	supplier	glue	Silver (Ag)	7440-22-4		0.355	mg	880893	10175
				supplier	glue	Isobornyl Methacrylate	7534-94-3		0.020	mg	49628	573
				supplier	glue	Acrylate resin	5888-33-5		0.020	mg	49628	573
				supplier	glue	Methyl acrylate polymer	87320-05-6		0.008	mg	19851	229
Bonding wires	M-011 Other inorganic materials	0.054	mg	supplier	wire	Copper (Cu)	7440-50-8		0.054	mg	1000000	1548
Encapsulation	M-015 Other organic materials	19.669	mg	supplier	mold compound	Silica, vitreous	60676-86-0		17.249	mg	876964	494382
				supplier	mold compound	Epoxy resin	85954-11-6		0.787	mg	40012	22557
				supplier	mold compound	Epoxy	29690-82-2		0.787	mg	40012	22557
				supplier	mold compound	phenol resin	Proprietary		0.590	mg	29996	16910
				supplier	mold compound	additive	Proprietary		0.197	mg	10016	5646
				supplier	mold compound	carbon black	1333-86-4		0.059	mg	3000	1691